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D	BOM DEFINITIONS									
	BOM	DEFINITION								_ _D
	BOARD_LEVEL_SHIELD	POPULATES TOP AND BOTTOM BOARD LEVEL SHIELDS. POPULATES M.2 BOARD LEVEL SHIELD								_ 1
	COMMON	ALL COMPONENTS WITH NO BOM PROPERTY								_
	DEBUG	COMPONENTS REQUIRED FOR BRING UP & DEBUG								-
	DEBUG_HDT	HDT-RELATED DEBUG COMPONENTS DEBUG TEST HOOKS. POPULATE IF BUILDING BARE PCBAS								-
	DEBUG_TP DEBUG_HEADER	DEBUG TEST HOOKS. POPULATE IF BUILDING BARE PCBAS DEBUG HEADERS WITH HEIGHT CLEARANCE ISSUES WITH CHASSIS. POPULATE ONLY ON PCBAS NOT INTENEDED FOR USE IN A CONSOLE ASSEMBLY								-
Ш	DEBUG_HEADER DEBUG_SHUNT	DEBUG HEADERS WITH HEIGHT CLEARANCE ISSUES WITH CHASSIS. POPULATE ONLY ON PCBAS NOT INTENEDED FOR USE IN A CONSOLE ASSEMBLY COMPONENTS WHICH ARE ON DEBUG BOARDS, BUT ARE REMOVED/SHORTED ON RETAIL								
	GDDR6_BASE	DUMMY PLACE HOLDER FOR GDDR6/DRAM. NEVER USE THIS IN THE RECIPE FILE.								-
	GDDR6_HYNIX	STUFFS HYNIX GDDR6								-
	GDDR6_SAMSUNG	STUFFS SAMSUNG GDDR6								-
	PCB_GI	FAB TYPE: GOLD								-
С	PCB_HG	FAB TYPE: HARD GOLD, RAISED PADS. FOR SOCKETED BOARDS								-
	PCB_OSP	FAB TYPE: ORGANIC SOLDERABILITY PRESERVATIVE GREEN SOLDERMASK								
	RETAIL	COMPONENTS STUFFED FOR A RETAIL CONSOLE. DO NOT USE WITH DEBUG								_
	RF	STUFFS 2.4/5GHZ FILTERS FOR DESENSE MITIGATION								_
	RTC_RETAIL	RTC CIRCUIT IMPLEMENTATION FOR RETAIL BOARDS								
	RTC_XDK	RTC CIRCUIT IMPLEMENTATION FOR XDK BOARDS								-
Н	SOC_BASE	DUMMY PLACE HOLDER FOR S	SOC. NEVER USE THIS IN T	THE RECIPE FILE.						- -
	SOC_EMPTY	DOES NOT STUFF ARDEN								
	SOC_INCLUDE	STUFFS ARDEN								-
В	SPI_FLASH_BASE SPI_FLASH_MACRONIX	DUMMY PLACE HOLDER FOR SPI FLASH. NEVER USE THIS IN THE RECIPE FILE. STUFFS MACRONIX SPI FLASH								-
	SPI_FLASH_WACKONIX SPI_FLASH_WINBOND	STUFFS WACKONIX SPI FLASH STUFFS WINBOND SPI FLASH								-
	VR_FIXED	SET ALL VRS TO FIXED VOLTAGES (NON-MARGINED). EXCLUDES V_MEMIO								- B
	VR_HEATSINK	STUFFS PEMNUTS FOR MOUNTING VRM HEATSINK (BARE PCBAS ONLY)								-
	INDUCTOR_CORE_BASE									-
	INDUCTOR_CORE_CHILIS									-
	INDUCTOR_CORE_EATON	STUFFS EATON INUDCTORS FOR HIGH POWER SOC DOMAINS								_
	INDUCTOR_CORE_SUNLOR	D STUFFS SUNLORD I	INUDCTORS FOR HIGH POWER	R SOC DOMAINS						- L
	VR_GFXCPU_BASE	DUMMY PLACE HOLDER FOR G	GFX/CPU POWER STAGES. NE	EVER USE THIS IN THE RECIPE F	ILE					_
	VR_GFXCPU_MP86955	STUFFS GFX/CPU POWER STA	AGES WITH THE MP86955 (8	B" WAFER QUAL)						_
	VR_GFXCPU_MP86965									_
	XTAL_25MHZ_BASE	DUMMY PLACE HOLDER FOR 2		HIS IN THE RECIPE FILE						-
	XTAL_25MHZ_KDS	STUFFS 25MHZ XTAL WITH T								-
	XTAL_25MHZ_NDK	STUFFS 25MHZ XTAL WITH T								-
A	XTAL_25MHZ_TXC	STUFFS 25MHZ XTAL WITH T		MEYED HEE WHIC IN THE DEATH	NE ETTE					-
	HDMI_LOAD_SWITCH_BAS	LOAD_SWITCH_BASE DUMMY PLACE HOLDER FOR HDMI LOAD SWITCH. NEVER USE THIS IN THE RECIPE FILE LOAD_SWITCH_DIODES STUFFS HDMI LOAD SWITCH WITH DIODES INC QUAL PART								- A
	-	IDMI_LOAD_SWITCH_DIODES STOFFS ADMI LOAD SWITCH WITH DIODES INC QUAL PART IDMI_LOAD_SWITCH_ST STUFFS HDMI LOAD SWITCH WITH STMICRO QUAL PART								
	HDMI_LOAD_SWITCH_TI STUFFS HDMI LOAD SWITCH WITH TEXAS INSTRUMENTS QUAL PART									-
	VR_MEMSOC_BASE									
	VR_MEMSOC_MP86910C									
	VR_MEMSOC_MP86912C STUFFS MEMIO/MEMPHY/SOC POWER STAGES WITH THE MP86912C (12" WAFER QUAL)									_
							MICROSOFT P	ROJECT NAME	PAGE CSA VI	 /ER
								oledo SoC		L.03
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